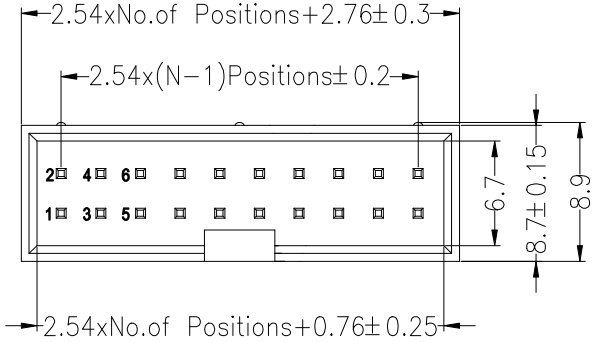
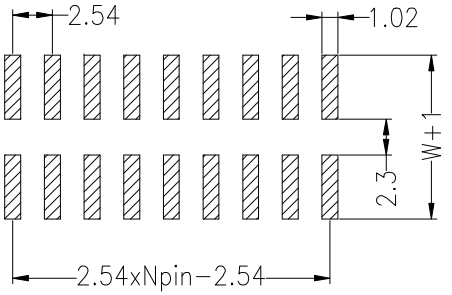
HSF RoHS FILE NO :E362610

SPECIFICATIONS
Rated Current:3.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:1000V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)



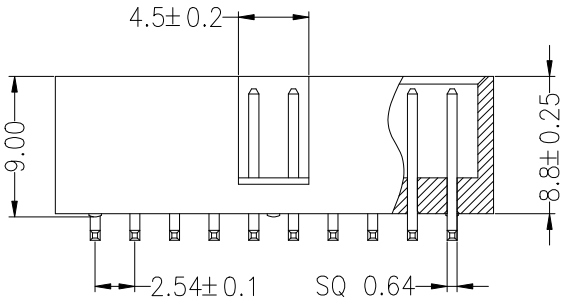
Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE± 0.05)

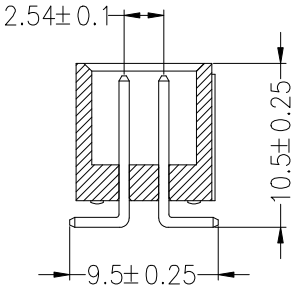


Ordering Information

3213 XX M XX X B K00 X 0X

- XX: No.of Pins 6−−64
- XX: Contact Plating
  - G0:Gold Flash
  - G1:1U" Gold
  - G2:1.5U" Gold
  - G3:2U" Gold
  - G4:3U" Gold
  - G5:5U" Gold
  - S0:Gold Flash/Tin
  - SN:Tin
- X: Insulator Material Option
  - C=BK−PA6T
  - D=BK−PA46
  - E=BK−PA9T
  - F=BK−LCP
- X: Packing
  - A=Tray
  - T=Tube
  - P=Tube+Cap
  - R=Reel+Cap





REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A0	2018.06.29	NEW DRAWING	

OPERATION		DRAW	Liu Miao	18.06.29	SCALE	FIT
X.X	± 0.30				UNIT	mm
X.XX	± 0.20	CHECK			SIZE	A4
X.XXX	± 0.10				SHEET	1/1
Angle	± 3°	APPROVE			PROJ.	
DIM	TOL					

WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD

PART NO.	3213XXMXXXBK00X0X
TITLE:	2.54mm Box Header H8.8mm SMT 短体